# 2SC3979, 2SC3979A

### Silicon NPN triple diffusion planar type

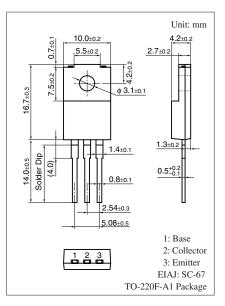
For high breakdown voltage high-speed switching

#### Features

- High-speed switching
- $\bullet$  High collector-base voltage (Emitter open)  $V_{CBO}$
- Wide safe operation area
- $\bullet$  Satisfactory linearity of forward current transfer ratio  $h_{\text{FE}}$
- Full-pack package which can be installed to the heat sink with one screw

Parameter	Symbol	Rating	Unit		
Collector-base voltage	2SC3979	V <sub>CBO</sub>	900	V	
(Emitter open)	2SC3979A		1 000		
Collector-emitter voltage	2SC3979	V <sub>CES</sub>	900	V	
(E-B short)	2SC3979A		1 000		
Collector-emitter voltage	V <sub>CEO</sub>	800	V		
Emitter-base voltage (Col	V <sub>EBO</sub>	7	V		
Base current	IB	1	А		
Collector current	I <sub>C</sub>	3	А		
Peak collector current	I <sub>CP</sub>	5	А		
Collector power	P <sub>C</sub>	40	W		
dissipation	$T_a = 25^{\circ}C$		2.0		
Junction temperature	Tj	150	°C		
Storage temperature	T <sub>stg</sub>	-55 to +150	°C		

#### Absolute Maximum Ratings $T_C = 25^{\circ}C$



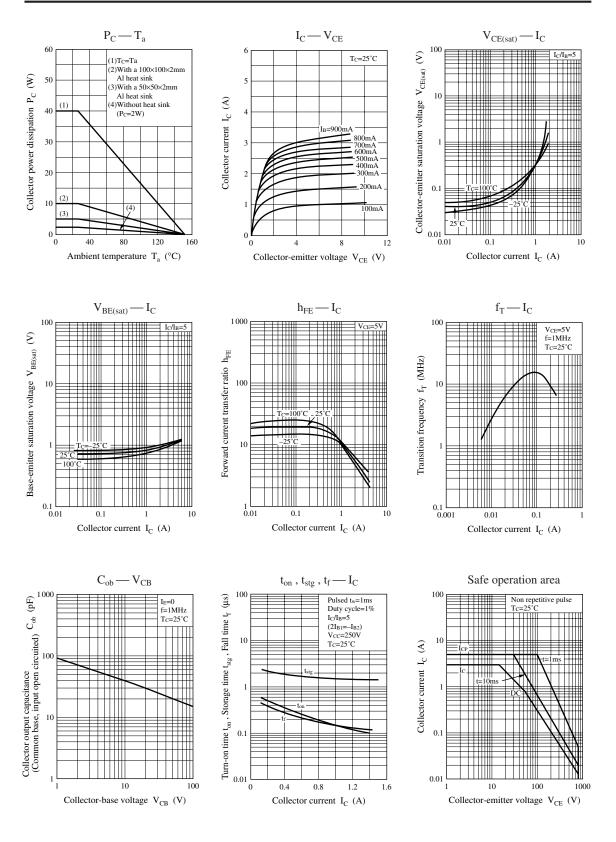
#### Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

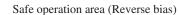
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)		V <sub>CEO</sub>	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0$	800			V
Collector-base cut-off current	2SC3979	I <sub>CBO</sub>	$V_{CB} = 900 \text{ V}, I_E = 0$			50	μΑ
(Emitter open)	2SC3979A		$V_{CB} = 1000$ V, $I_E = 0$			50	
Emitter-base cutoff current (Collector open)		I <sub>EBO</sub>	$V_{EB} = 7 V, I_C = 0$			50	μΑ
Forward current transfer ratio		h <sub>FE1</sub>	$V_{CE} = 5 V, I_C = 0.1 A$	8			_
		h <sub>FE2</sub>	$V_{CE} = 5 V, I_C = 0.8 A$	6			
Collector-emitter saturation	voltage	V <sub>CE(sat)</sub>	$I_C = 0.8 \text{ A}, I_B = 0.16 \text{ A}$			1.5	V
Base-emitter saturation voltage		V <sub>BE(sat)</sub>	$I_C = 0.8 \text{ A}, I_B = 0.16 \text{ A}$			1.5	V
Transition frequency		$f_{T}$	$V_{CE} = 5 \text{ V}, I_C = 0.15 \text{ A}, f = 1 \text{ MHz}$		10		MHz
Turn-on time		ton	$I_{C} = 0.8 A$			0.7	μs
Storage time		t <sub>stg</sub>	$I_{B1} = 0.16 \text{ A}, I_{B2} = -0.32 \text{ A}$			2.5	μs
Fall time		t <sub>f</sub>	$V_{CC} = 250 \text{ V}$			0.3	μs

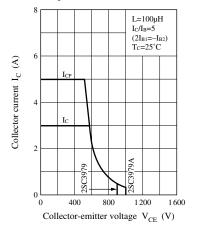
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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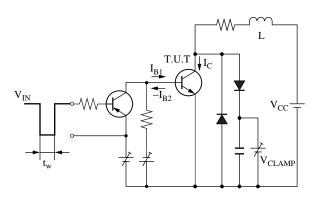
## **Panasonic**

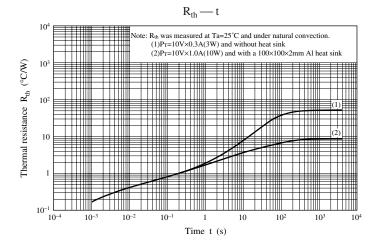






Safe operation area (Reverse bias) measurement circuit





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